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Abstract of the Disclosure

A method for producing printed circuit boards, which comprises the following method steps:

(A) coating both sides of a through-plated copper laminate using a negative electrodeposition-resist;

(B) structuring the resist coating by imagewise exposure to light, the through-platings being covered by a mask, and then developing;

(C) applying a metal resist by electrodeposition;

(D) removing the crosslinked negative photoresist remaining on the laminate;

(E) removing the bare copper by means of an etching solution; and

(F) removing the metal resist by means of a stripper solution,

yields through-platings having reduced annular rings.

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